


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

REVISION HISTORY			
ECO	REV	DESCRIPTION	APPR
	2	PRODUCTION	TOM G.
			DATE
			11-29-12

APPROVALS		<div> <b>LINEAR TECHNOLOGY</b> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY</div>			
PCB DES.	HZ	TITLE: TOP ASSEMBLY DRAWING			
APP ENG.	TOM G.	17V VIN SYNCHRONOUS STEP-DOWN REGULATOR WITH ULTRA-LOW QUIESCENT CURRENT			
		SIZE	IC NO. LTC3621EMS8E	REV.	
		N/A	DEMO CIRCUIT 1863A	2	
SCALE = NONE		FILENAME: DC1863A-2.PCB		SHT 1 OF 1	